

Product data sheet

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2.ANODE

3.GATE

1.KATHODE

SOT-89

FEATURES

Current-I_{GT}: 200 μ A I_{TRMS}: 0.8 A V_{RRM}/ V_{DRM}: MCR100-6/MS: 400 V MCR100-8/MS: 600 V Operating and storage junction temperature range T_J, T_{stg}: -55°C to +150°C



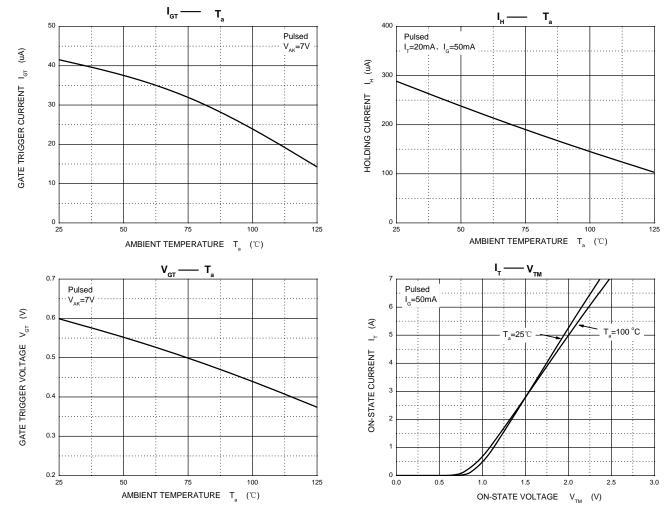
ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol		Test conditions	Min	Мах	Unit
On state voltage	V _{TM} *		I _{TM} =1A		1.7	V
Gate trigger voltage	V _{GT}		V _{AK} =7V		0.8	V
Peak Repetitive forward and reverse blocking voltage MCR100-6 MCR100-8	V _{drm} and V _{rrm}		I _{DRM} = 10 μΑ	400 600		V
Peak forward or reverse blocking Current	I _{DRM} I _{RRM}		V _{AK} = Rated V _{DRM} or V _{RRM}		10	μA
Holding current	Ι _Η		I_{HL} = 20mA ,Vak = 7V		5	mA
		A2	V _{AK} =7V	5	15	μA
		A1		15	30	μA
Gate trigger current	I _{GT}	А		30	80	μΑ
		В		80	200	μA

* Forward current applied for 1 ms maximum duration, duty cycle <1%.





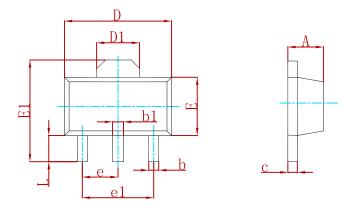


Typical Characteristics



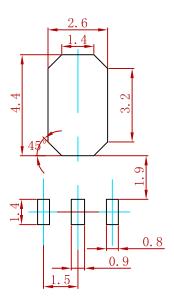


PACKAGE MECHANICAL DATA



Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min Max		Min	Max		
А	1.400	1.600	0.055	0.063		
b	0.320	0.520	0.013	0.020		
b1	0.400	0.580	0.016	0.023		
С	0.350	0.440	0.014	0.017		
D	4.400	4.600	0.173	0.181		
D1	1.550	REF.	0.061 REF.			
E	2.300	2.600	0.091	0.102		
E1	3.940	4.250	0.155	0.167		
e	1.500	TYP.	0.060 TYP.			
e1	3.000	3.000 TYP.		0.118 TYP.		
L	0.900	1.200	0.035	0.047		

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MCR100-X/MS	SOT-89	1000



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